INTEGRATED CIRCUITS

DATA SHEET

CBT16213

24-bit bus exchange switch with 12-bit output enables

Objective specification





24-bit bus exchange switch with 12-bit output enables

CBT16213

FEATURES

- 5 Ω switch connection between two ports
- TTL compatible control input levels
- Package options include plastic shrink small outline (SSOP) and thin shrink small outline (TSSOP)

DESCRIPTION

The CBT16213 provides 24 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The CBT16213 operates as 24-bit bus switch or a 12-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0–S2) terminals.

The CBT16213 is characterized for operation from -40 to +85 °C.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25 °C; GND = 0 V	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay An to Yn	$C_L = 50 \text{ pF}; V_{CC} = 5 \text{ V}$	0.25	ns
C _{IN}	Input capacitance	V _I = 0 V or V _{CC}	4.5	pF
C _{OUT}	Output capacitance	Outputs disabled; $V_O = 0 \text{ V or } V_{CC}$	11.5	pF
I _{CCZ}	Total supply current	Outputs disabled; V _{CC} = 5.5 V	3	μΑ

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	-40 to +85 °C	CBT16213DL	CBT16213DL	SOT371-1
56-Pin Plastic TSSOP Type II	-40 to +85 °C	CBT16213DGG	CBT16213DGG	SOT364-1

FUNCTION TABLE

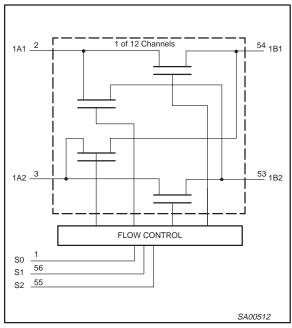
S2	S1	S0	A1	A2	FUNCTION
L	L	L	Z	Z	Disconnect
L	L	Н	B1	Z	A1 = B1
L	Н	L	B2	Z	A1 = B2
L	Н	Н	Z	B1	A2 = B1
Н	L	L	Z	B2	A2 = B2
Н	L	Н	A2 & B2	A1 & B2	A1 = A2 = B2
Н	Н	L	B1	B2	A1 = B1, A2 = B2
Н	Н	Н	B2	B1	A1 = B2, A2 = B1

H = High voltage level

L = Low voltage level

Z = High impedance "off" state

LOGIC SYMBOL

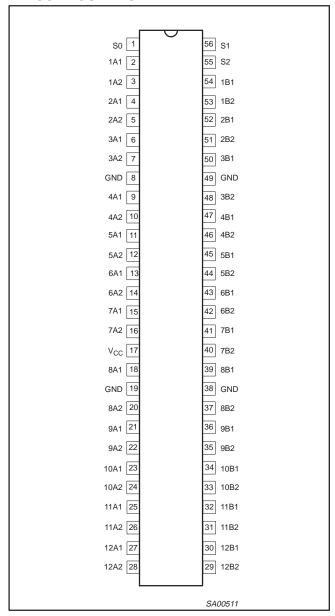


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PIN CONFIGURATION



PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 56, 55	S0, S1, S2	Data select
2, 4, 6, 9, 11, 13, 15, 18, 21, 23, 25, 27	1A1-12A1	A1 channel
3, 5, 7, 10, 12, 14, 16, 20, 22, 24, 26, 28	1A2-12A2	A2 channel
54, 52, 50, 47, 45, 43, 41, 39, 36, 34, 32, 30	1B1, 12B1	B1 channel
53, 51, 48, 46, 44, 42, 40, 37, 35, 33, 31, 29	1B2, 12B2	B2 channel
8, 19, 38, 49	GND	Ground (0 V)
17	V _{CC}	Positive supply voltage

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V _I < 0	-50	mA
VI	DC input voltage ³		-0.5 to +7.0	V
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V
lout	DC output current	output in Low state	128	mA
T _{stg}	Storage temperature range		-65 to +150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
STMBOL	PARAMETER	Min	Max	UNII
V _{CC}	DC supply voltage	4.0	5.5	V
V _{IH}	High-level input voltage	2.0	_	V
V _{IL}	Low-level Input voltage	_	0.8	V
T _{amb}	Operating free-air temperature range	-40	+85	°C

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DC ELECTRICAL CHARACTERISTICS

				LIMITS]
SYMBOL	PARAMETER	TEST CONDITIONS	T _{amb}	= −40 °C to	+85 °C	UNIT
			Min	Typ ¹	Max	1
V _{IK}	Input clamp voltage	$V_{CC} = 4.5 \text{ V}; I_I = -18 \text{ mA}$	_	_	-1.2	V
	Input lookogo gurrent	V _{CC} = 0 V; V _I = 5.5 V	_	_	10	
l II	Input leakage current	$V_{CC} = 5.5 \text{ V}; V_{I} = \text{GND or } 5.5 \text{ V}$	_	_	±1	μΑ
I _{CC}	Quiescent supply current ²	$V_{CC} = 5.5 \text{ V}; I_O = 0 \text{ V}, V_I = V_{CC} \text{ or GND}$	_	_	3	μΑ
Δl _{CC}	Additional supply current per input pin ²	V_{CC} = 5.5 V, one input at 2.7 V, other inputs at V_{CC} or GND		_	2.5	mA
C _I	Control pins	V _I = 3 V or 0 V	_	4.5	_	pF
	Power-off leakage current, B port	V 2 V 2 v 0 V 5 0 5 4 2 v 5 2 V	T -	11.5	_	pF
C _{IO(OFF)}	Power-off leakage current, A port	$V_{O} = 3 \text{ V or } 0 \text{ V}; \text{ S0, S1, or S2} = V_{CC}$	_	11.5	_	pF
		$V_{CC} = 4.0 \text{ V}; V_1 = 2.4 \text{ V}; I_1 = 15 \text{ mA}$	_	14	21	
	A to B or B to A	V _{CC} = 4.5 V; V ₁ = 0 V; I _I = 64 mA	_	5	7]
	A 10 B 01 B 10 A	$V_{CC} = 4.5 \text{ V}; V_1 = 0 \text{ V}; I_1 = 30 \text{ mA}$	_	5	7	1
r _{on} 3		$V_{CC} = 4.5 \text{ V}; V_1 = 2.4 \text{ V}; I_1 = 15 \text{ mA}$	_	8	15	Ω
on		$V_{CC} = 4.0 \text{ V}; V_1 = 2.4 \text{ V}; I_1 = 15 \text{ mA}$	_	22	33	52
	A1 to A2	V _{CC} = 4.5 V; V ₁ = 0 V; I _I = 64 mA	$_{\text{C}}$ = 4.5 V; V ₁ = 0 V; I _I = 64 mA — 10			
	AT IO AZ	V _{CC} = 4.5 V; V ₁ = 0 V; I _I = 30 mA	_	10	14]
		V _{CC} = 4.5 V; V ₁ = 2.4 V; I _I = 15 mA		16	22	<u> </u>

- All typical values are at V_{CC} = 5 V, T_{amb} = 25 °C
 This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.
- 3. Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

AC CHARACTERISTICS

 $GND = 0 V; t_{R;} C_{L} = 50 pF$

SYMBOL	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = +5.0) V ± 0.5 V	V _{CC} =	4.0 V	UNIT
				Min	Max	Min	Max	
	t Decreasion date: 1		B or A	_	0.25	_	0.25	ns
t _{pd}	Propagation delay ¹	A1	A2	_	0.5	_	0.5	ns
	Output enable time	S	A or B	3.2	11.1	_	12.4	ns
^t en	to High and Low level		A2 and B2	4	10.9	_	13.3	ns
+	Output disable time	S	A or B	2.3	11.9	_	12.4	ns
t _{dis}	from High and Low level	S0	A2 and B2	5.7	12	_	12.8	ns

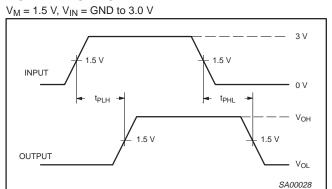
NOTES:

^{1.} This parameter is warranted but not production tested. The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

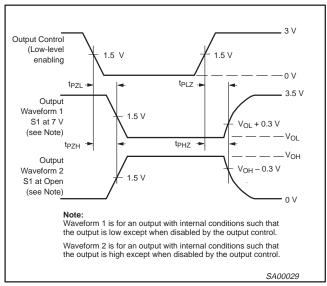
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AC WAVEFORMS

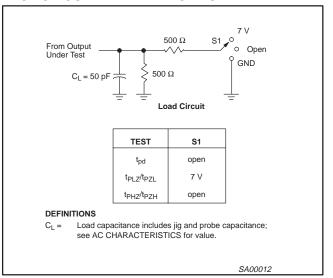


Waveform 1. Input (An) to Output (Yn) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

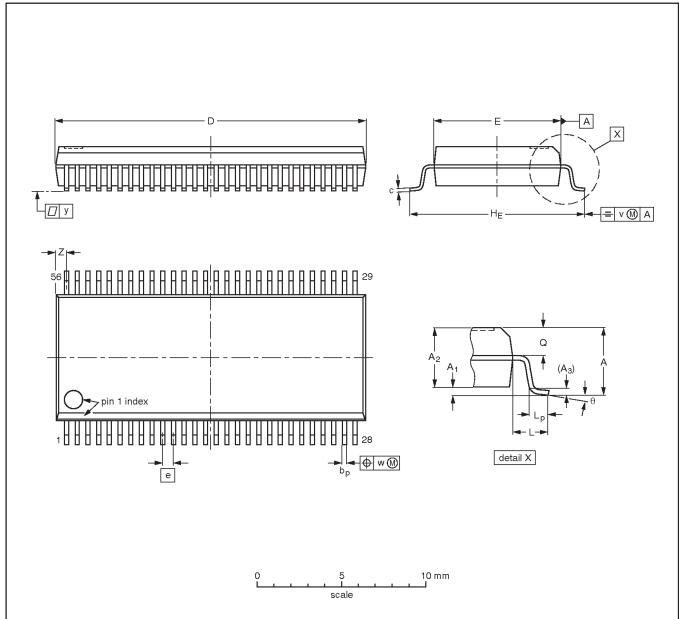
TEST CIRCUIT AND WAVEFORMS



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SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm

SOT371-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE			
VERSION	IEC	IEC JEDEC EIAJ			PROJECTION	ISSUE DATE
SOT371-1		MO-118				95-02-04 99-12-27

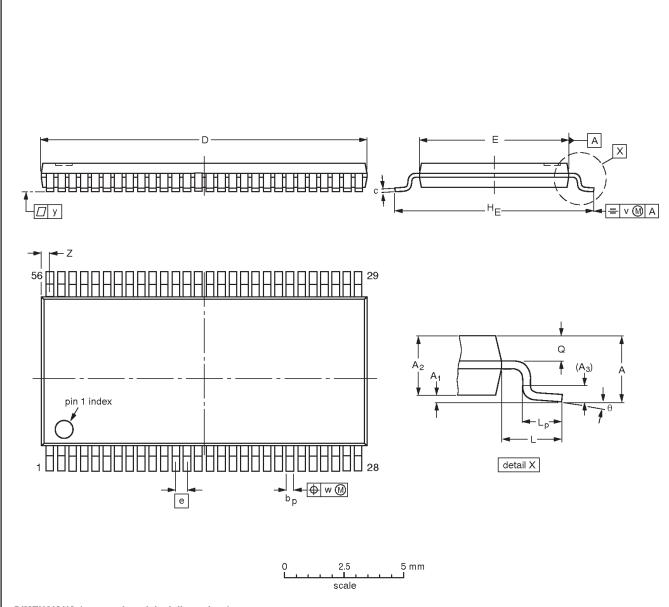
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TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1 mm

SOT364-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	Α1	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1.0	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT364-1		MO-153				-95-02-10- 99-12-27

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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